ABSTRACT

A wiring substrate section 2 is provided between a radiation detecting section 1, which is formed of a scintillator 10 and a PD array 15, and signal processing elements 30 and 32 for processing a detected signal outputted from the PD array 15, and the wiring substrate section 2 has a wiring substrate 20 which is formed of a glass material having a radiation shielding function and in which a conductive member 21 serving as a conduction path for guiding the detected signal therethrough is provided in a through hole 20c. Relative to the through hole 20c of the wiring substrate 20, the signal processing elements 30 and 32 of the signal processing section 3, located downstream of the wiring substrate 20, are each disposed in an area excluding those areas on the extension of the through holes 20c, and this allows the signal processing elements 30 and 32 not to be seen through the through holes 20c. This arrangement realizes a radiation detector which suppresses radiation made incident on the signal processing means located downstream of the wiring substrate.